

OSRAM LUW H9GP

Datasheet

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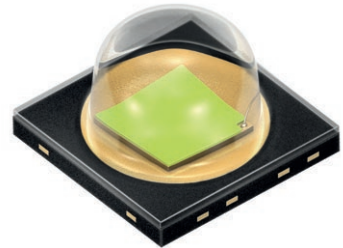
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OSLON® Black

LUW H9GP

OSLON Black Series combines thermal stability with high performance and reliability in a compact black package. It has a metal lead frame and a tried and tested lens design. The LED can be used wherever there are large fluctuations in temperature and a large amount of light is needed from a small area.



Applications

- Static Forward Lighting
- Static Signaling

Features

- Package: SMD epoxy package with silicone lens
- Chip technology: ThinGaN
- Typ. Radiation: 90°
- Color: Cx = 0.31, Cy = 0.32 acc. to CIE 1931 (• ultra white)
- Corrosion Robustness Class: 3B
- Qualifications: AEC-Q102 Qualified
- Color temperature: 6500K
- ESD: 8 kV acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)

Ordering Information

Type	Color temperature	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ Φ_V	Ordering Code
LUW H9GP-KYLY-4C8E-1	6500 K	82 ... 150 lm	Q65111A0924

Maximum Ratings

Parameter	Symbol		Values
Operating Temperature	T_{op}	min.	-40 °C
		max.	125 °C
Storage Temperature	T_{stg}	min.	-40 °C
		max.	125 °C
Junction Temperature	T_j	max.	150 °C
Junction Temperature for short time applications*	T_j	max.	175 °C
Forward current	I_F	min.	100 mA
$T_s = 25\text{ °C}$		max.	1000 mA
Surge current	I_{FS}	max.	2500 mA
$t \leq 10\text{ }\mu\text{s}$; $D = 0.016$; $T_s = 25\text{ °C}$			
ESD withstand voltage acc. to ANSI/ESDA/JEDEC JS-001 (HBM, Class 3B)	V_{ESD}		8 kV
Reverse current ²⁾	I_R	max.	200 mA

* The median lifetime (L70/B50) for $T_j = 175\text{ °C}$ is 100h.

Characteristics

$I_F = 350 \text{ mA}$; $T_S = 25 \text{ °C}$

Parameter	Symbol		Values
Chromaticity Coordinate ³⁾	Cx	typ.	0.31
	Cy	typ.	0.32
Viewing angle at 50% I_V	2ϕ	typ.	90 °
Forward Voltage ⁴⁾ $I_F = 350 \text{ mA}$	V_F	min.	2.75 V
		typ.	3.20 V
		max.	3.75 V
Reverse voltage (ESD device)	$V_{R \text{ ESD}}$	min.	45 V
Reverse voltage ²⁾ $I_R = 20 \text{ mA}$	V_R	max.	1.2 V
Real thermal resistance junction/solderpoint ⁵⁾	$R_{thJS \text{ real}}$	typ.	5.4 K / W
		max.	7.3 K / W

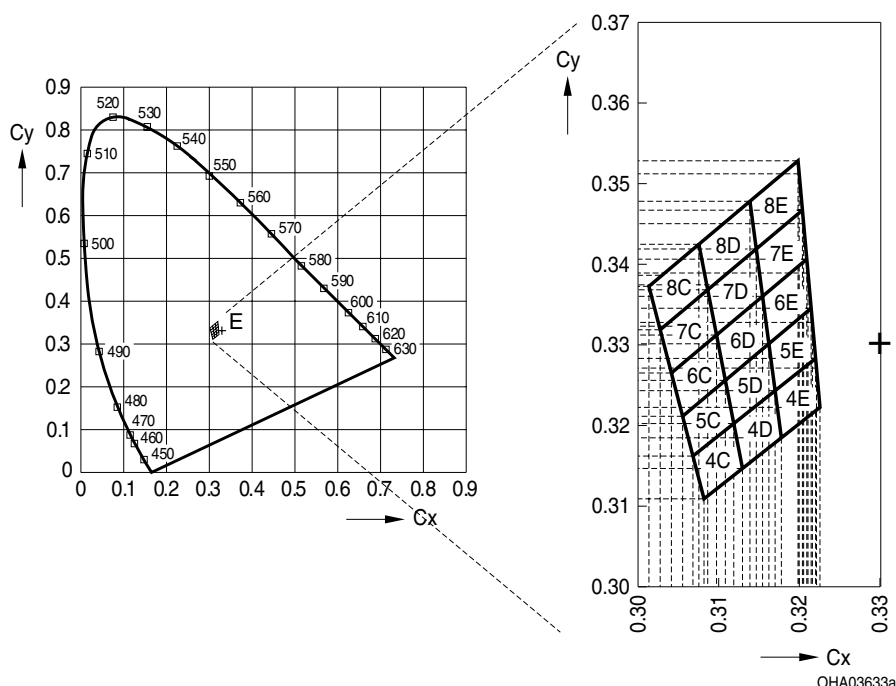
Brightness Groups

Group	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ min. Φ_V	Luminous Flux ¹⁾ $I_F = 350 \text{ mA}$ max. Φ_V	Luminous Intensity ⁶⁾ $I_F = 350 \text{ mA}$ typ. I_v
KY	82 lm	97 lm	43 cd
KZ	97 lm	112 lm	50 cd
LX	112 lm	130 lm	58 cd
LY	130 lm	150 lm	67 cd

Forward Voltage Groups

Group	Forward Voltage ⁴⁾ $I_F = 350 \text{ mA}$ min. V_F	Forward Voltage ⁴⁾ $I_F = 350 \text{ mA}$ max. V_F
8E	2.75 V	3.00 V
8F	3.00 V	3.25 V
8G	3.25 V	3.50 V
8H	3.50 V	3.75 V

Chromaticity Coordinate Groups ³⁾



Chromaticity Coordinate Groups ³⁾

Group	Cx	Cy	CCT	Group	Cx	Cy	CCT	Group	Cx	Cy	CCT
4C	0.3081	0.3049	6500	5D	0.3119	0.3162	6500	6E	0.3162	0.3282	6500
	0.3068	0.3113	6500		0.3108	0.3229	6500		0.3154	0.3352	6500
	0.3119	0.3162	6500		0.3162	0.3282	6500		0.3210	0.3408	6500
	0.3130	0.3095	6500		0.3170	0.3212	6500		0.3216	0.3334	6500
4D	0.3130	0.3095	6500	5E	0.3170	0.3212	6500	7C	0.3041	0.3240	6500
	0.3119	0.3162	6500		0.3162	0.3282	6500		0.3028	0.3304	6500
	0.3170	0.3212	6500		0.3216	0.3334	6500		0.3087	0.3363	6500
	0.3178	0.3142	6500		0.3221	0.3262	6500		0.3098	0.3296	6500
4E	0.3178	0.3142	6500	6C	0.3055	0.3177	6500	7D	0.3098	0.3296	6500
	0.3170	0.3212	6500		0.3041	0.3240	6500		0.3087	0.3363	6500
	0.3221	0.3262	6500		0.3098	0.3296	6500		0.3146	0.3422	6500
	0.3226	0.3189	6500		0.3108	0.3229	6500		0.3154	0.3352	6500
5C	0.3068	0.3113	6500	6D	0.3108	0.3229	6500	7E	0.3154	0.3352	6500
	0.3055	0.3177	6500		0.3098	0.3296	6500		0.3146	0.3422	6500
	0.3108	0.3229	6500		0.3154	0.3352	6500		0.3205	0.3481	6500
	0.3119	0.3162	6500		0.3162	0.3282	6500		0.3210	0.3408	6500

Group	Cx	Cy	CCT	Group	Cx	Cy	CCT	Group	Cx	Cy	CCT
8C	0.3028	0.3304	6500	8D	0.3087	0.3363	6500	8E	0.3146	0.3422	6500
	0.3015	0.3368	6500		0.3076	0.3430	6500		0.3138	0.3492	6500
	0.3076	0.3430	6500		0.3138	0.3492	6500		0.3200	0.3554	6500
	0.3087	0.3363	6500		0.3146	0.3422	6500		0.3205	0.3481	6500

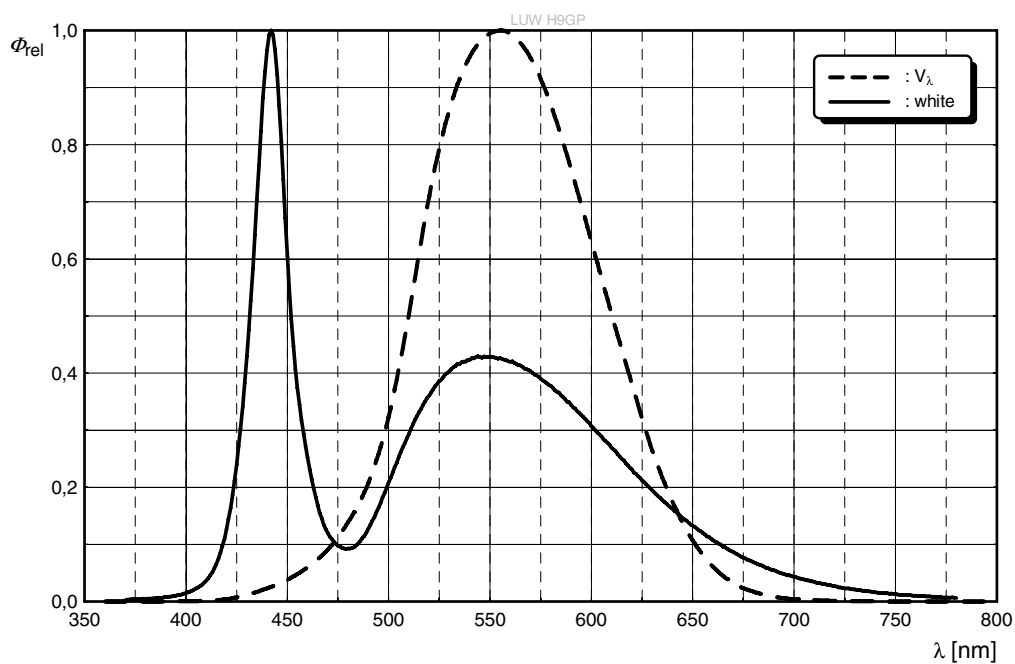
Group Name on Label

Example: KY-4C-8E

Brightness	Color Chromaticity	Forward Voltage
KY	4C	8E

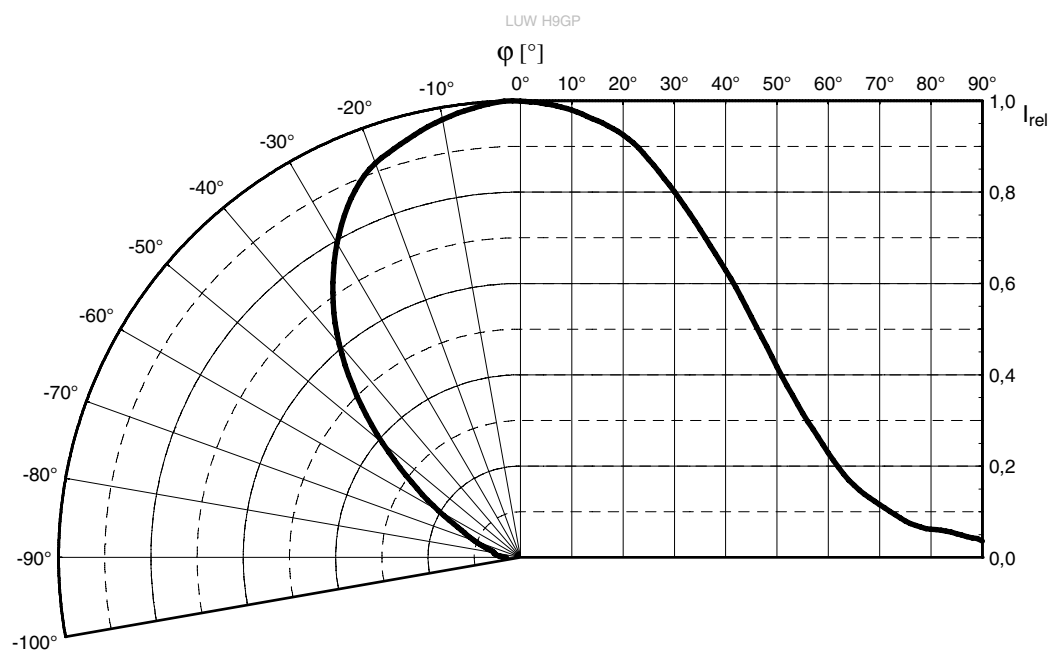
Relative Spectral Emission ⁶⁾

$\Phi_{\text{rel}} = f(\lambda)$; $I_F = 350 \text{ mA}$; $T_S = 25 \text{ }^\circ\text{C}$



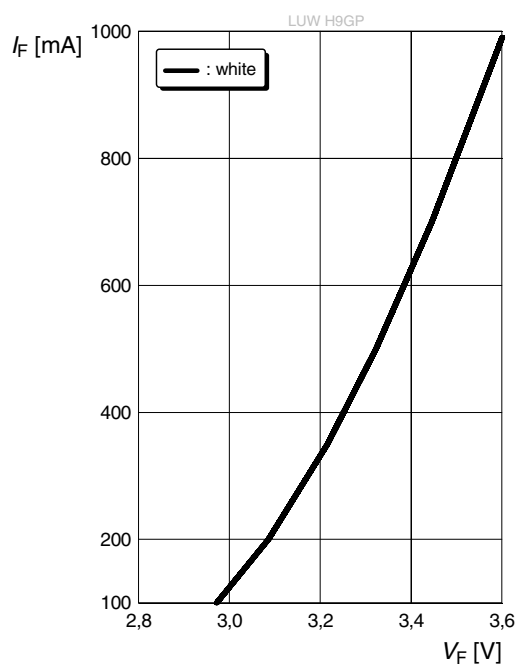
Radiation Characteristics ⁶⁾

$I_{\text{rel}} = f(\phi)$; $T_S = 25 \text{ }^\circ\text{C}$



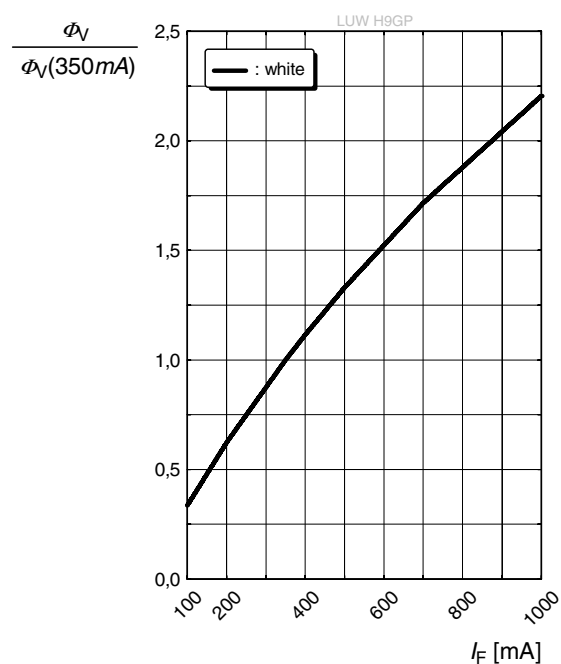
Forward current ^{6), 7)}

$$I_F = f(V_F); T_S = 25\text{ °C}$$



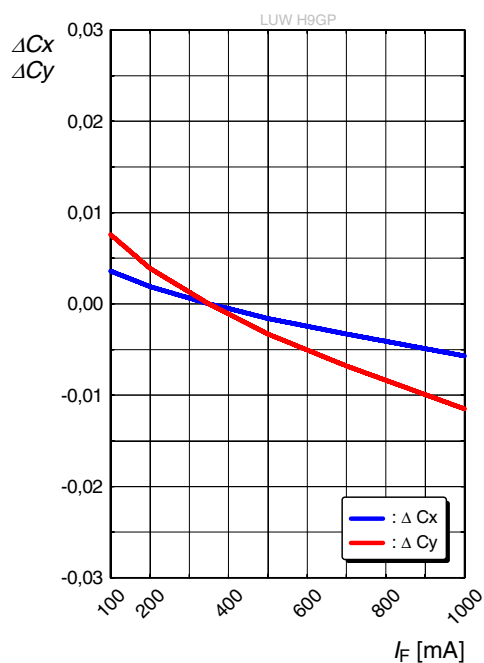
Relative Luminous Flux ^{6), 7)}

$$\Phi_V / \Phi_V(350\text{ mA}) = f(I_F); T_S = 25\text{ °C}$$



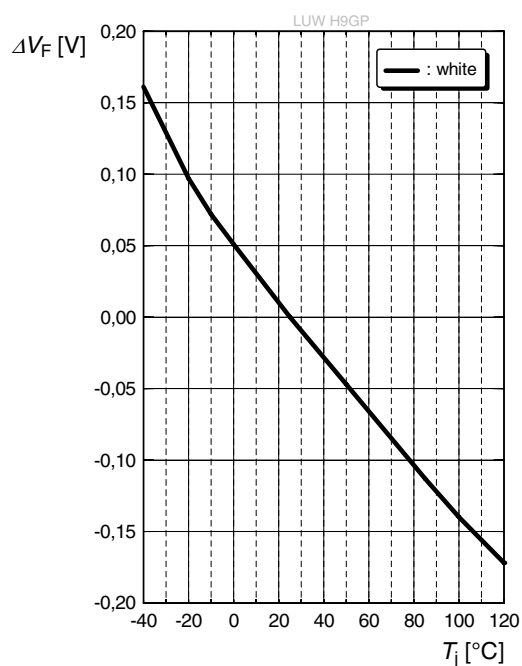
Chromaticity Coordinate Shift ⁶⁾

$$\Delta Cx, \Delta Cy = f(I_F); T_S = 25\text{ °C}$$



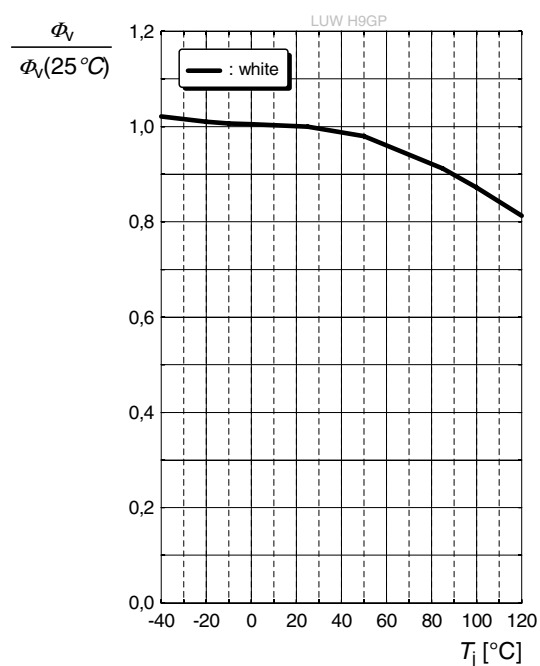
Forward Voltage ⁶⁾

$$\Delta V_F = V_F - V_F(25^\circ\text{C}) = f(T_j); I_F = 350\text{ mA}$$



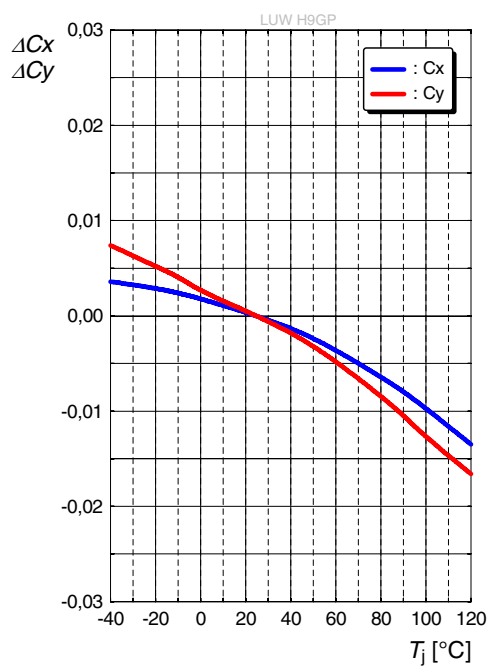
Relative Luminous Flux ⁶⁾

$$\Phi_V / \Phi_V(25^\circ\text{C}) = f(T_j); I_F = 350\text{ mA}$$



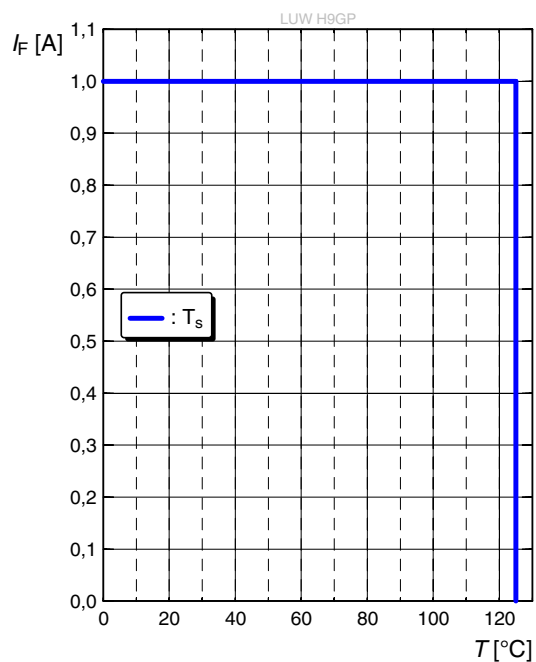
Chromaticity Coordinate Shift ⁶⁾

$$\Delta Cx, \Delta Cy = f(T_j); I_F = 350\text{ mA}$$



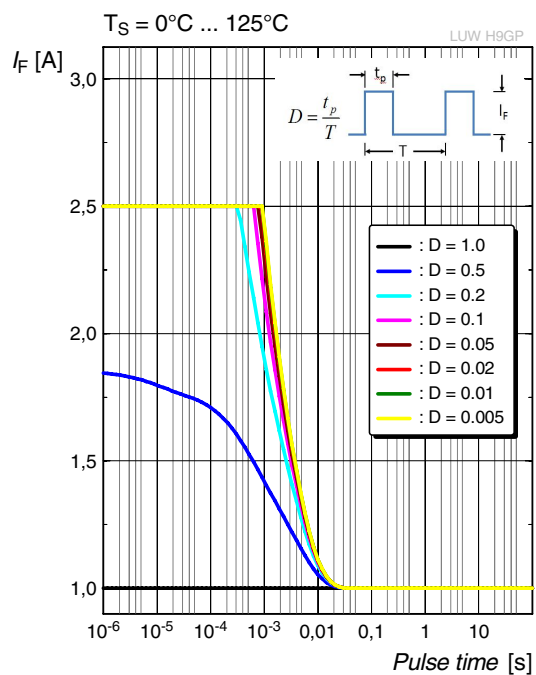
Max. Permissible Forward Current ⁵⁾

$$I_F = f(T)$$

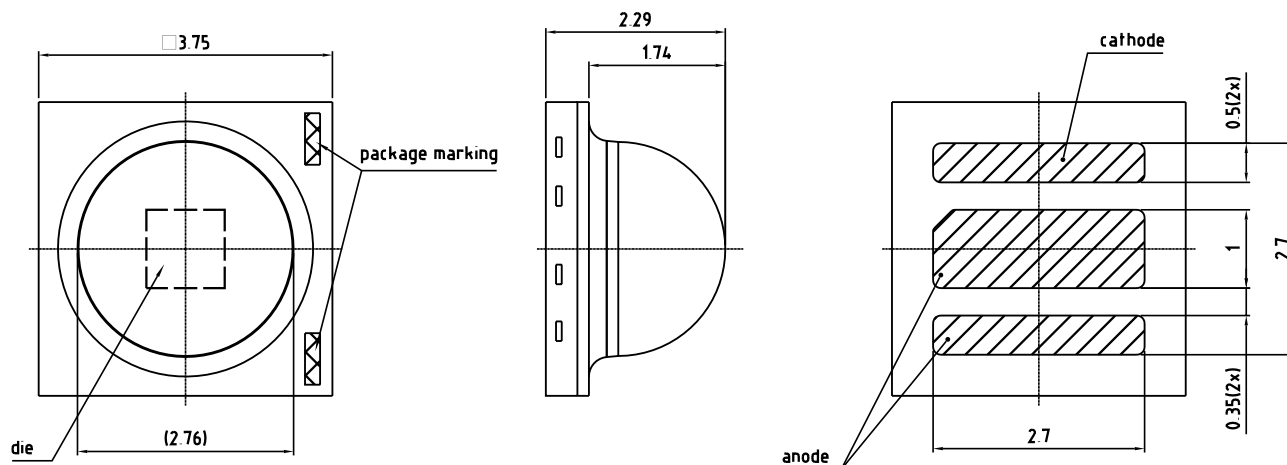


Permissible Pulse Handling Capability

$$I_F = f(t_p); D: \text{Duty cycle}$$



Dimensional Drawing ⁸⁾



general tolerance ± 0.1

lead finish Au 

C63062-A4068-A11-01

Further Information:

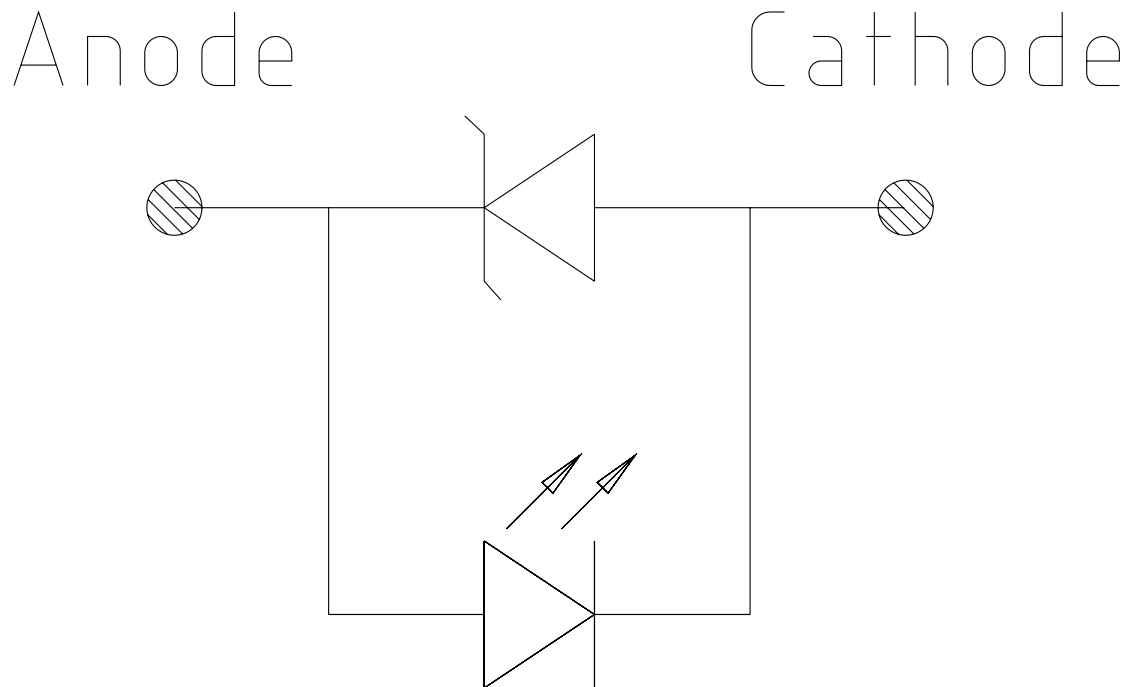
Approximate Weight: 32.0 mg

Package marking: Cathode

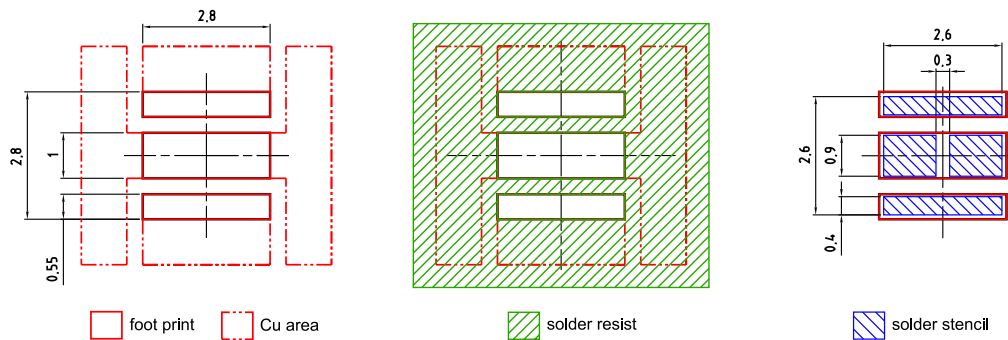
Corrosion test: Class: 3B
Test condition: 40°C / 90 % RH / 15 ppm H₂S / 14 days (stricter than IEC 60068-2-43)

ESD advice: The device is protected by ESD device which is connected in parallel to the Chip.

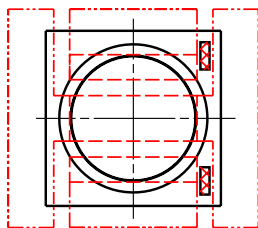
Electrical Internal Circuit



Recommended Solder Pad ⁸⁾



Component Location on Pad
(Component is generic for round lens design)

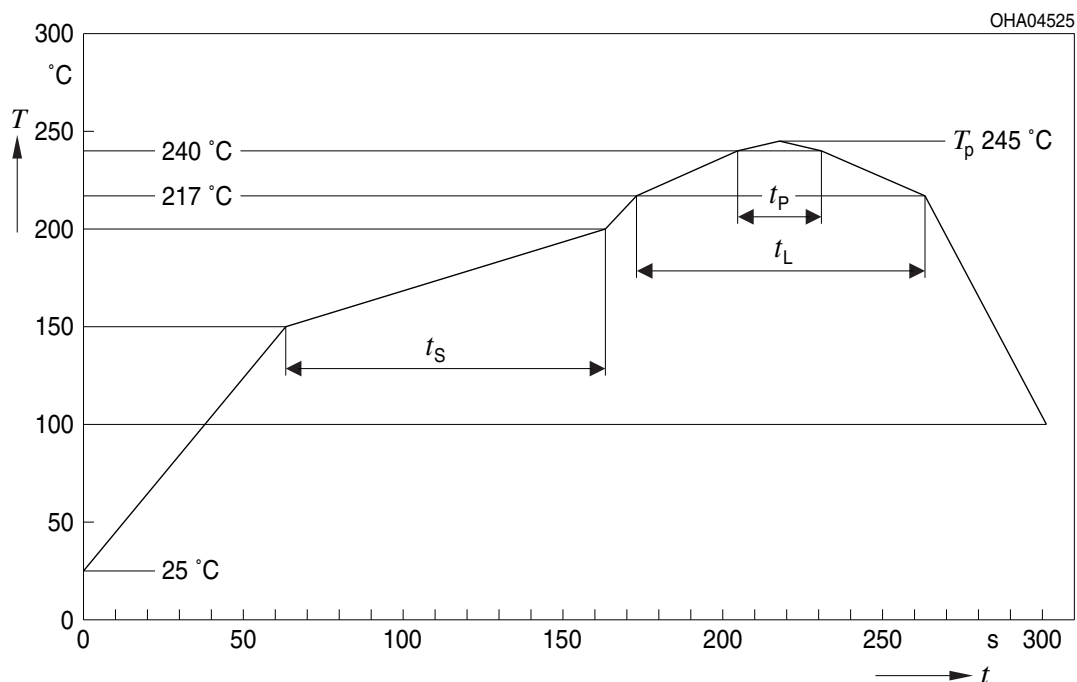


E062.3010.91 -06

For superior solder joint connectivity results we recommend soldering under standard nitrogen atmosphere. In case the PCB layout of the application is intended to be used with other OSRON derivatives or in future developed OSRON derivatives, the heat sink must not be electrically connected to anode or cathode solder pad because of possible chip inverted polarity. Package not suitable for ultra sonic cleaning. To ensure a high solder joint reliability and to minimize the risk of solder joint cracks, the customer is responsible to evaluate the combination of PCB board and solder paste material for his application.

Reflow Soldering Profile

Product complies to MSL Level 2 acc. to JEDEC J-STD-020E

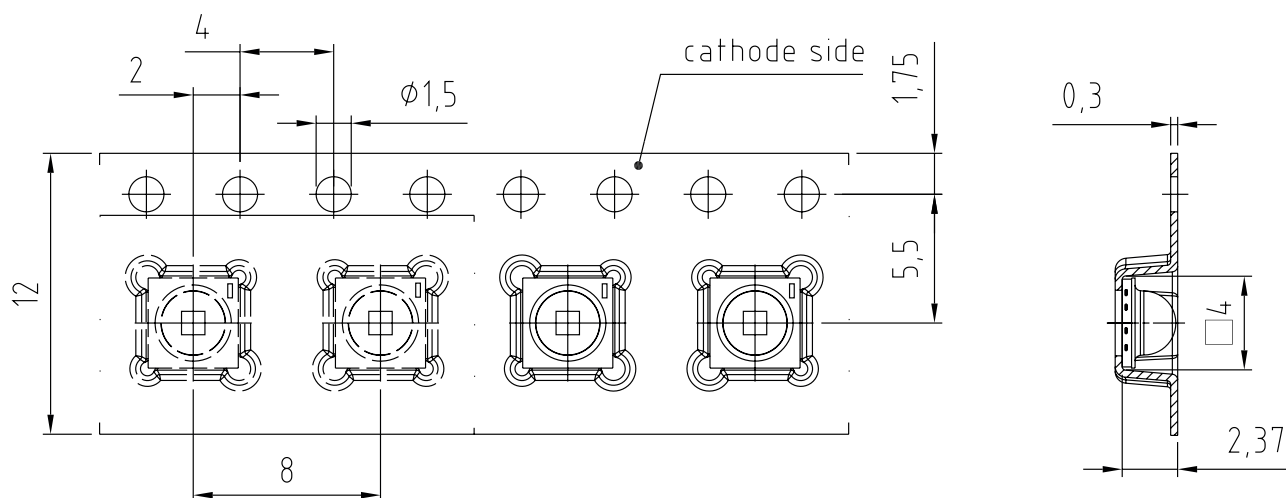


Profile Feature	Symbol	Pb-Free (SnAgCu) Assembly			Unit
		Minimum	Recommendation	Maximum	
Ramp-up rate to preheat ^{*)} 25 °C to 150 °C			2	3	K/s
Time t_s T_{Smin} to T_{Smax}	t_s	60	100	120	s
Ramp-up rate to peak ^{*)} T_{Smax} to T_p			2	3	K/s
Liquidus temperature	T_L		217		°C
Time above liquidus temperature	t_L		80	100	s
Peak temperature	T_p		245	260	°C
Time within 5 °C of the specified peak temperature $T_p - 5$ K	t_p	10	20	30	s
Ramp-down rate* T_p to 100 °C			3	6	K/s
Time 25 °C to T_p				480	s

All temperatures refer to the center of the package, measured on the top of the component

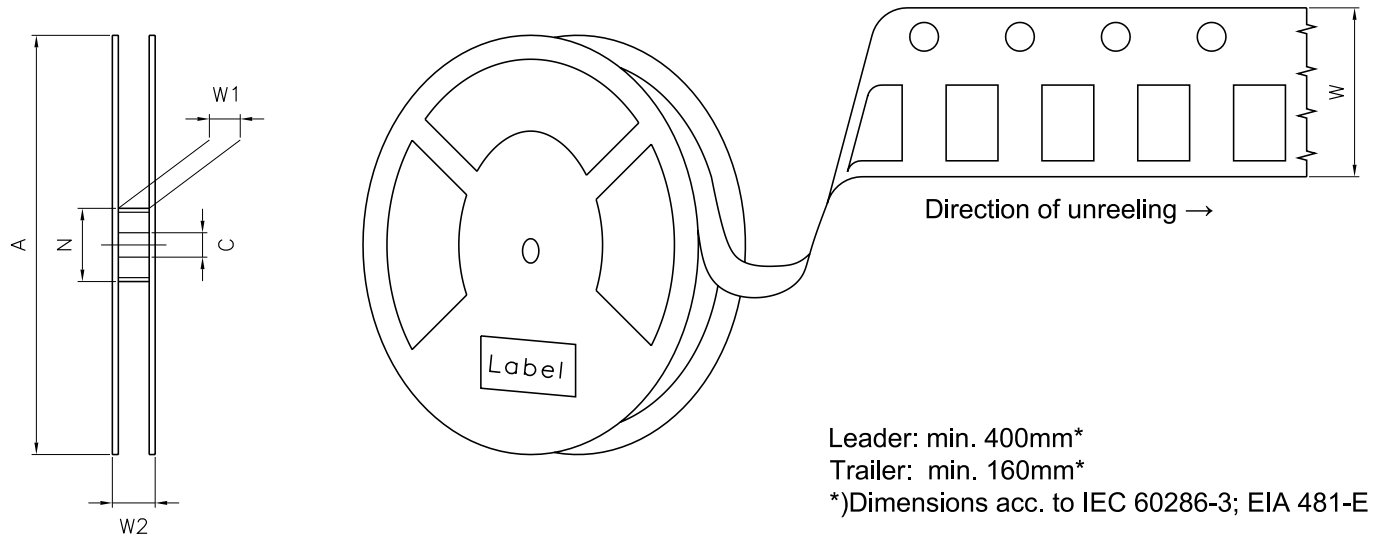
* slope calculation DT/Dt : Dt max. 5 s; fulfillment for the whole T-range

Taping ⁸⁾



C63062-A4068-B10 -12






Tape and Reel ⁹⁾



Reel Dimensions

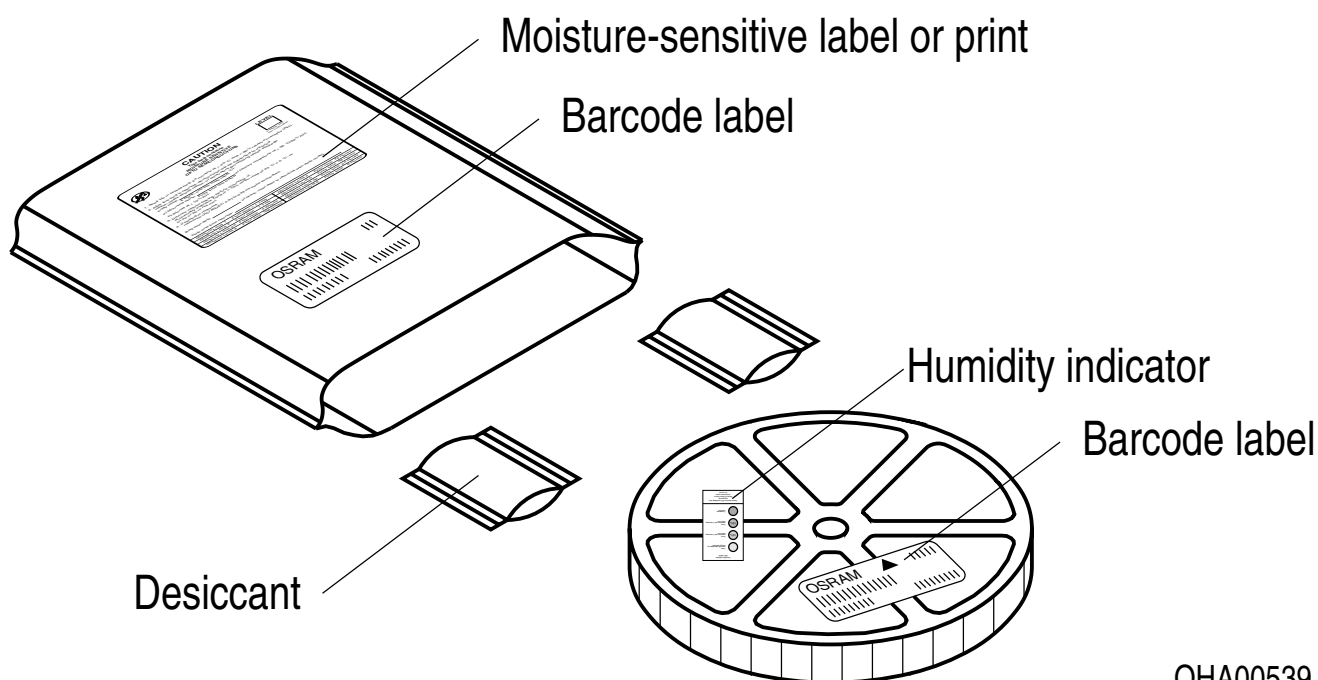
A	W	N _{min}	W ₁	W _{2 max}	Pieces per PU
180 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	600
330 mm	12 + 0.3 / - 0.1 mm	60 mm	12.4 + 2 mm	18.4 mm	3000

Barcode-Product-Label (BPL)

OSRAM		LX XXXX	BIN1: XX-XX-X-XXX-X		
(6P) BATCH NO:	1234567890	RoHS Compliant			
		 ML Temp ST X XXX °C X			
(1T) LOT NO:	1234567890	(9D) D/C:		1234	
		Pack: RXX DEMY XXX X_X123_1234.1234 X			
(X) PROD NO:	123456789	(Q) QTY:	9999	(G) GROUP:	XX-XX-X-X
					

OHA04563

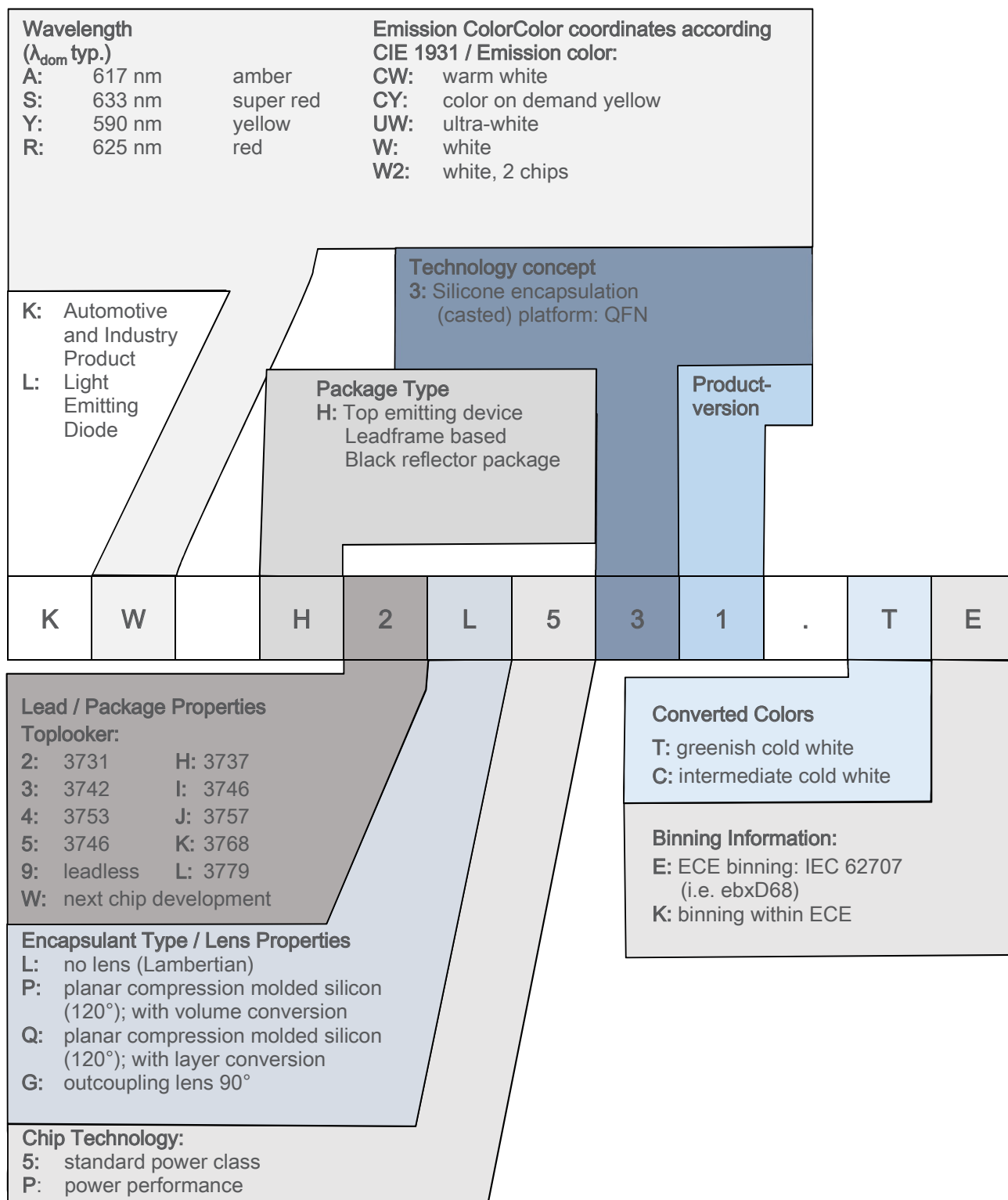
Dry Packing Process and Materials ⁸⁾



OH A00539

Moisture-sensitive product is packed in a dry bag containing desiccant and a humidity card according JEDEC-STD-033.

Type Designation System



Notes

The evaluation of eye safety occurs according to the standard IEC 62471:2006 (photo biological safety of lamps and lamp systems). Within the risk grouping system of this IEC standard, the device specified in this data sheet fall into the class **low risk (exposure time 100 s)**. Under real circumstances (for exposure time, conditions of the eye pupils, observation distance), it is assumed that no endangerment to the eye exists from these devices. As a matter of principle, however, it should be mentioned that intense light sources have a high secondary exposure potential due to their blinding effect. When looking at bright light sources (e.g. headlights), temporary reduction in visual acuity and afterimages can occur, leading to irritation, annoyance, visual impairment, and even accidents, depending on the situation.

Subcomponents of this device contain, in addition to other substances, metal filled materials including silver. Metal filled materials can be affected by environments that contain traces of aggressive substances. Therefore, we recommend that customers minimize device exposure to aggressive substances during storage, production, and use. Devices that showed visible discoloration when tested using the described tests above did show no performance deviations within failure limits during the stated test duration. Respective failure limits are described in the IEC60810.

For further application related information please visit <https://ams-osram.com/support/application-notes>

Disclaimer

Attention please!

The information describes the type of component and shall not be considered as assured characteristics. Terms of delivery and rights to change design reserved. Due to technical requirements components may contain dangerous substances.

For information on the types in question please contact our Sales Organization.

If printed or downloaded, please find the latest version on our website.

Packing

Please use the recycling operators known to you. We can also help you – get in touch with your nearest sales office. By agreement we will take packing material back, if it is sorted. You must bear the costs of transport. For packing material that is returned to us unsorted or which we are not obliged to accept, we shall have to invoice you for any costs incurred.

Product and functional safety devices/applications or medical devices/applications

Our components are not developed, constructed or tested for the application as safety relevant component or for the application in medical devices.

Our products are not qualified at module and system level for such application.

In case buyer – or customer supplied by buyer – considers using our components in product safety devices/ applications or medical devices/applications, buyer and/or customer has to inform our local sales partner immediately and we and buyer and /or customer will analyze and coordinate the customer-specific request between us and buyer and/or customer.

Glossary

- 1) **Brightness:** Brightness values are measured during a current pulse of typically 25 ms, with an internal reproducibility of $\pm 8\%$ and an expanded uncertainty of $\pm 11\%$ (acc. to GUM with a coverage factor of $k = 3$).
- 2) **Reverse Operation:** This product is intended to be operated applying a forward current within the specified range. Applying any continuous reverse bias or forward bias below the voltage range of light emission shall be avoided because it may cause migration which can change the electro-optical characteristics or damage the LED.
- 3) **Chromaticity coordinate groups:** Chromaticity coordinates are measured during a current pulse of typically 25 ms, with an internal reproducibility of ± 0.005 and an expanded uncertainty of ± 0.01 (acc. to GUM with a coverage factor of $k = 3$).
- 4) **Forward Voltage:** The forward voltage is measured during a current pulse of typically 8 ms, with an internal reproducibility of $\pm 0.05\text{ V}$ and an expanded uncertainty of $\pm 0.1\text{ V}$ (acc. to GUM with a coverage factor of $k = 3$).
- 5) **Thermal Resistance:** $R_{th\text{ max}}$ is based on statistic values (6σ) used for Derating.
- 6) **Typical Values:** Due to the special conditions of the manufacturing processes of semiconductor devices, the typical data or calculated correlations of technical parameters can only reflect statistical figures. These do not necessarily correspond to the actual parameters of each single product, which could differ from the typical data and calculated correlations or the typical characteristic line. If requested, e.g. because of technical improvements, these typ. data will be changed without any further notice.
- 7) **Characteristic curve:** In the range where the line of the graph is broken, you must expect higher differences between single devices within one packing unit.
- 8) **Tolerance of Measure:** Unless otherwise noted in drawing, tolerances are specified with ± 0.1 and dimensions are specified in mm.
- 9) **Tape and Reel:** All dimensions and tolerances are specified acc. IEC 60286-3 and specified in mm.

Revision History

Version	Date	Change
1.9	2020-01-30	<ul style="list-style-type: none"> Features Further Information Recommended Solder Pad Reel Dimensions Schematic Transportation Box Dimensions of Transportation Box Type Designation System Notes Disclaimer
1.10	2023-09-29	<ul style="list-style-type: none"> New Layout Applications Dimensional Drawing Electrical Internal Circuit Recommended Solder Pad Notes Disclaimer Glossary



EU RoHS and China RoHS compliant product

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按照中国的相关法规和标准，
不含有毒有害物质或元素。

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